

Title (en)  
PROCESS FOR MANUFACTURING A COMPONENT, PROCESS FOR MANUFACTURING A COMPONENT ARRANGEMENT, COMPONENT AND COMPONENT ARRANGEMENT

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES BAUELEMENTS, VERFAHREN ZUR HERSTELLUNG EINER BAUELEMENTANORDNUNG, BAUELEMENT UND BAUELEMENTANORDNUNG

Title (fr)  
PROCÉDÉ DE RÉALISATION D'UN COMPOSANT, PROCÉDÉ DE RÉALISATION D'UN SYSTÈME DE COMPOSANTS, COMPOSANT ET SYSTÈME DE COMPOSANTS CORRESPONDANTS

Publication  
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Application  
**EP 09779687 A 20090609**

Priority  

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Abstract (en)  
[origin: WO2010006849A2] The invention proposes a process for manufacturing a component, wherein, in a first manufacturing step, a basic structure having a substrate, a membrane and a cavern region is provided, wherein the membrane is arranged substantially parallel to a plane of principal extent of the substrate, wherein the cavern region is arranged between the substrate and the membrane, wherein the cavern region has an access opening and wherein, in a second manufacturing step, a first conductive layer is arranged at least partially in the cavern region and, in particular, on a second side of the membrane which faces towards the substrate perpendicularly to the plane of principal extent.

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Citation (search report)  
See references of WO 2010006849A2

Citation (examination)  

- US 2003222335 A1 20031204 - HIRANO KOICHI [JP], et al
- US 2006273430 A1 20061207 - HUA YAPING [CN], et al
- US 2005084998 A1 20050421 - HORNING ROBERT D [US], et al

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